

Electroplating Solutions

nb technologies
consulting engineers



NBT has designed specialised electroplating solutions based on many years of engineering experience and application expertise for MEMS, semiconductor industries, PCBs and photovoltaic technologies.



Product	Application	Features
NB Semiplate Au 100	Surface finishing Bond pads	very stable bath, sulfite based very uniform thickness, very shiny surface, arsenite grain refiner room temperature plating
NB Semiplate Au 100 TL	Surface finishing Bond pads	free of arsenite , bright surface, very stable bath, sulfite based very uniform thickness, room temperature plating
NB Semiplate Au 200	Surface finishing Bond pads	free of arsenite , semi bright surface, very stable bath, sulfite based very uniform thickness, high rate, room temperature plating
NB Semiplate Cu 100	Conducting lines Sacrificial layers	sulfuric acid based, shiny surface, uniform thickness, low stress
NB Semiplate Cu 150	Conducting lines Sacrificial layers	designed for inert anode process sulfuric acid based, shiny surface, uniform thickness
NB Semiplate Cu 200	Conducting lines Sacrificial layers	single-additive system, sulfuric acid based, shiny surface, uniform thickness
NB Semiplate Sn 100	Soldering Surface finish	MSA based, good bonding
NB Semiplate Sn 150	Soldering Surface finish	designed for inert anode process, MSA based, good bonding
NB Semiplate Ni 100	Mechanical elements, Barrier layer	high purity bath and deposit, medium temperature plating, low stress, controlled mechanical properties
NB Semiplate NiMn 100	Mechanical elements in high temperature application (switches, relays, tethers)	low-creep Ni, stable grain size under temperature and mechanical load
NB Semiplate In 100	Soldering or bonding	alkaline, non-cyanide matte, fine-grained, surface
NB Semiplate Ag 100	Conductors, surface finish	alkaline, cyanide-free Ag, compatible with resist mask
Nb Semiplate Bi 100	Absorbers in space applications	pure bismuth plating solution
NB Semiplate Pd 200	Surface finish, barrier	alkaline bath, 0,3 to 1µm thickness, compatible with resist
sun-NiSi	Porous Si etching and Ni plating from one solution	ethanol-free, low HF concentration plates Ni in nm-pores, excellent adhesion

Jan 2021

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